



Infineon and Micron Develop Next-Generation Data Storage Solution for HD-SIM Cards; Collaboration to Push HD-SIM Card Capacity Beyond 128MB

November 3, 2008 at 12:00 AM EST

Neubiberg, Germany and Boise, Idaho, USA , Monday, November 03, 2008 – Infineon Technologies AG (FSE/NYSE: IFX), the world's leading supplier of integrated circuits (ICs) for chip cards, and Micron Technology, Inc. (NYSE: MU), one of the world's leading providers of advanced memory semiconductor solutions, today announced a strategic technology collaboration for the development of high-density subscriber identity module (HD-SIM) cards reaching beyond 128 megabytes (MBs).

HD-SIM cards are ideal for delivering expanded storage and greater services for mobile applications while improving the operator's processes. Combining high density with improved security enables operators to offer graphically-rich, value-added services such as mobile banking and contactless mobile ticketing. Further, operators can securely update or delete applications through their wireless network while new applications, services and settings can be downloaded or pushed to the HD-SIM at any time to maintain fast time-to-market. However, this growth in functionality also means that storage solutions for the SIM need to keep evolving to take advantage of faster processing and communication speeds, ultimately delivering the higher memory capacity that these applications require.

To answer these needs, Infineon and Micron will develop an innovative, high-density solution. Working in close technical collaboration, both companies are leveraging their respective expertise to architect modular chip solutions that combine an Infineon security microcontroller with Micron's innovative NAND flash memory with features designed specifically for HD-SIM applications. Micron will manufacture the NAND on 50-nanometer (nm) and 34-nm process technology. The joint solution is designed to be efficiently integrated into HD-SIM cards and will enable these cards to effectively reach beyond 128MBs of capacity and offer a host of other new features, including:

- **High Density:** Serial NAND Flash memory provides the most cost-effective solution for 128MBs or greater capacity on HD-SIMs.
- **ECC (error correction code) Circuits:** Incorporated internally on the Micron NAND to relieve the data error correction burden from the HD-SIM microcontroller and streamline the overall security design.
- **Superior Power Management:** Designed for European Telecommunications Standards Institute (ETSI) compliance. The Infineon/Micron HD-SIM solution operates across the voltage range of 1.8-volts to 3.3-volts, complying with ETSI's recommendations for low-operating current.
- **Easy Migration:** The security microcontroller concept includes an optimized and cost effective packaging solution allowing for easy migration between NOR- and NAND-based technologies as it features an aligned application protocol interface (API) and related software stack. Also, operating system software developed for existing SIM cards can be easily reused.

"The demands for more robust storage and applications are driving the mobile market into its next phase," said Bill Lauer, senior director of Marketing at Micron Technology. "Micron is renowned for world-class technology and NAND innovation—we're committed to developing strategic storage solutions that are well past a one-size-fits-all model. This joint HD-SIM solution provides much greater densities than were available before and we believe this technology will continue to enable new and exciting applications for the mobile market."

"Infineon envisions a new role of future SIM cards that will be capable of audio and video mass content storage and even Flash card replacement. Infineon is committed to enabling the entire HD-SIM market with a comprehensive HD-SIM product portfolio from single-digit megabytes to 2 gigabytes that offers the right level of performance and security," said Dr. Helmut Gassel, vice president and general manager of the Chip Card and Security division at Infineon Technologies. "Our customers—chip card manufacturers and mobile network operators alike—benefit from our intelligent HD-SIM microcontroller family concept enabling comfortable migration between NOR and NAND-based technologies, limited R&D cost and minimized qualification effort for the HD-SIM platform. And that results in their high flexibility in the emerging HD-SIM market allowing fast reaction in multiple use cases."

Prototypes are expected to be available in fall of 2009 and will be sold in die form or in an economic chip card IC package.

Further Information

For further information on the product portfolio of chip card ICs at Infineon, please see: www.infineon.com/security

For more information on Micron's memory product portfolio, please visit: www.nand.com

Infineon at Cartes Trade Show

During the three day Cartes Trade Show (November 4-6, 2008), Infineon is demonstrating its comprehensive chip card IC portfolio at Booth #4L002 in Hall 4.

For more information on the company's show highlights at Cartes, visit www.infineon.com/cartes

About Infineon

Infineon Technologies AG, Neubiberg, Germany, offers semiconductor and system solutions addressing three central challenges to modern society: energy efficiency, communications, and security. In the 2007 fiscal year (ending September), the company reported sales of Euro 7.7 billion (including Qimonda sales of Euro 3.6 billion) with approximately 43,000 employees worldwide (including approximately 13,500 Qimonda employees). With a global presence, Infineon operates through its subsidiaries in the U.S. from Milpitas, CA, in the Asia-Pacific region from Singapore, and in Japan from Tokyo. Infineon is listed on the Frankfurt Stock Exchange and on the New York Stock Exchange (ticker symbol: IFX).

Further information is available at www.infineon.com.

Contact Information:

For the Business and Trade Press: INFCCS20081x.0xxe

Media Relations Technology:
Worldwide Headquarters
U.S.A.
Asia
Japan
Investor Relations

Name:
Monika Sonntag
Mitch Ahiers
Chi Kang David Ong
Hirota Shiroguchi
EU/APAC/USA/CAN

Phone:
+49 89 234 24497
+1 408 503 2791
+65 6876 3070
+81 3 5745 7340
+49 89 234 26655

Email:
monika.sonn timer@infineon.com
mitch.ahiers@infineon.com
david.ong@infineon.com
hirotaka.shiroguchi@infineon.com
investor.relations@infineon.com

About Micron

Micron Technology, Inc., is one of the world's leading providers of advanced semiconductor solutions. Through its worldwide operations, Micron manufactures and markets DRAMs, NAND flash memory, other semiconductor components, and memory modules for use in leading-edge computing, consumer, networking, and mobile products. Micron's common stock is traded on the New York Stock Exchange (NYSE) under the MU symbol. To learn more about Micron Technology, Inc., visit www.micron.com.

Contact Information:

Micron Technology, Inc. Contact:

Kirstin Bordner
Micron Technology, Inc.
208.368.5487
kbordner@micron.com

Micron Technology, Inc.
8000 S. Federal Way
PO Box 6
Boise, ID 83707-0006
208.368.4000

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This press release contains forward-looking statements regarding the production of the Micron / Infineon joint HD-SIM card solution. Actual events or results may differ materially from those contained in the forward-looking statements. Please refer to the documents the Company files on a consolidated basis from time to time with the Securities and Exchange Commission, specifically the Company's most recent Form 10-K and Form 10-Q. These documents contain and identify important factors that could cause the actual results for the Company on a consolidated basis to differ materially from those contained in our forward-looking statements (see Certain Factors). Although we believe that the expectations reflected in the forward-looking statements are reasonable, we cannot guarantee future results, levels of activity, performance or achievements.

This press release contains forward-looking statements regarding the production of HD-SIM Cards. Actual events or results may differ materially from those contained in the forward-looking statements. Please refer to the documents that Micron files on a consolidated basis from time to time with the Securities and Exchange Commission, specifically Micron's most recent Form 10-K and Form 10-Q. These documents contain and identify important factors that could cause the actual results for Micron on a consolidated basis to differ materially from those contained in its forward-looking statements (see Certain Factors). Although Micron believes that the expectations reflected in the forward-looking statements are reasonable, Micron cannot guarantee future results, levels of activity, performance or achievements. Micron is under no duty to update any of the forward-looking statements after the date of this press release to conform to actual results.

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This news release is available online at:

www.infineon.com/press/ and at abea-45yxq.client.shareholder.com/releases.cfm

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Contacts

Kirstin Bordner
Micron Technology, Inc.
+1 (208) 599-0184/mobile
+1 (208) 368-5487/direct
kbordner@micron.com